

Product Texts

LNP THERMOCOMP EC008 compound is based on Polyetherimide (PEI) resin containing 40% carbon fiber. Added features of this grade include: Electrically Conductive.

Processing/Physical Characteristics

	Value	Unit	Test Standard
ASTM Data			
Mold Shrinkage, MD	0.2	mm/mm	ASTM D 955
Mold Shrinkage, TD	0.3	mm/mm	ASTM D 955

Mechanical properties

	Value	Unit	Test Standard
ISO Data			
Tensile Modulus	27000	MPa	ISO 527
Yield stress	211	MPa	ISO 527
Strain at break	0.9	%	ISO 527
Flexural modulus	22200	MPa	ISO 178
Izod impact strength, +23°C, 4mm	25	kJ/m ²	ISO 180/1U
Izod notched impact strength, +23°C, 4mm	8	kJ/m ²	ISO 180/1A

Thermal properties

	Value	Unit	Test Standard
ISO Data			
Temp. of deflection under load, 1.80 MPa	214	°C	ISO 75-1/-2

Electrical properties

	Value	Unit	Test Standard
ASTM Data			
Surface Resistivity	1000	Ohm	ASTM D 257

Other properties

	Value	Unit	Test Standard
Density	1440	kg/m ³	ISO 1183

Processing Recommendation Injection Molding

	Value	Unit	Test Standard
Pre-drying - Temperature	150	°C	-
Pre-drying - Time	4 - 6	h	-
Processing humidity	≤0.02	%	-
Melt temperature	360 - 400	°C	-
Mold temperature	140 - 180	°C	-
Zone 1	360 - 380	°C	-
Zone 2	370 - 390	°C	-
Zone 3	380 - 400	°C	-
Back pressure	0.3 - 0.7	MPa	-

Characteristics**Processing**

Injection Molding

Regional Availability

North America, Europe, Asia Pacific

Special Characteristics

Increased electrical conductivity